

**ABSTRACT****LEAD FRAME AND METHOD OF
MANUFACTURING THE LEAD FRAME**

5 A method for manufacturing a lead frame including the steps of
electrocleaning the surface of a thin plate material, electropolishing the
electrocleaned thin plate material, removing inclusions on the surface of the
electropolished thin plate material, rinsing the inclusion-removed thin plate
material with an acidic solution, and forming multi-plated layers on the rinsed
10 material. The lead frame manufactured by the method has 5 or less inclusions
each having approximately $1\ \mu\text{m}$, on the surface area of $1600\ \mu\text{m}^2$, which
impede a wire bonding property or solder wettability of the lead frame.

FIG. 5